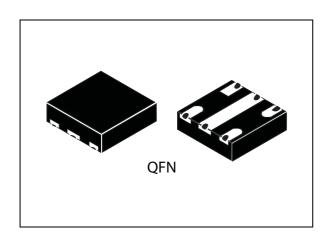
# life.augmented

#### EMIF02-010ABRY

# IPAD™ integrated low pass filter with ESD protection for BroadR Reach™ interface in automotive

Datasheet - production data



#### **Features**

- Attenuation profile compliant with BroadR Reach™ requirements from -40 °C to 125 °C
- Return loss (S<sub>dd11</sub>) at 60 MHz: -20dB
- Components matching: 1% (between line 1 and 2)
- · Package:
  - Dimensions: 3.0 x 3.0 mm
  - Pitch: 1.1 μm
  - Wettable flank QFN
- · AEC-Q101 compliant

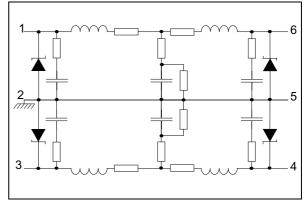
#### Complies with the following standards

- IEC 61000-4-2 exceeds level 4 (330  $\Omega$  / 150 pF):
  - 15 kV (air discharge)
  - 15 kV (contact discharge)
- ISO 10605 (330 Ω / 330 pF):
  - 15 kV (air discharge)
  - 15kV (contact discharge)
- ISO 7637-3:
  - Pulse 3a: -150 V
  - Pulse 3b: +100 V

#### **Description**

The EMIF02-01OABRY is a highly integrated solution designed to suppress EMI noise in BroadR Reach  $^{\text{TM}}$  interfaces in automotive applications. This low pass filter includes a 15 kV ISO10605 protection and is housed in a 3 x 3 mm² wettable flanks QFN.

Figure 1. EMIF02-01OABRY equivalent circuit



TM: IPAD is a trademark of STMicroelectronics.

Characteristics EMIF02-01OABRY

## 1 Characteristics

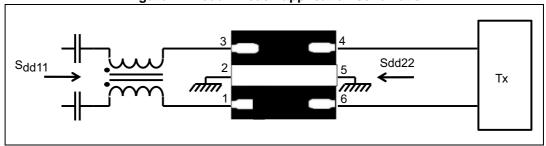
Table 1. Absolute ratings ( $T_{amb} = 25 \, ^{\circ}C$ )

| Symbol           | Parameter and test conditions Value                                                                  |               |    |  |  |
|------------------|------------------------------------------------------------------------------------------------------|---------------|----|--|--|
| V                | External pins (pin1 and pin3): IEC 61000-4-2 (330 $\Omega$ / 150 pF) air discharge contact discharge | 15<br>15      | kV |  |  |
| V <sub>PP</sub>  | External pins (pin1 and pin3): ISO 10605 (330 $\Omega$ / 330 pF) air discharge contact discharge     | 15<br>15      |    |  |  |
| $V_{PP}$         | Transceiver side pins: HBM (pin4 and pin6)                                                           | 2             | kV |  |  |
| T <sub>L</sub>   | Maximum lead temperature for soldering 10 s                                                          | 260           | °C |  |  |
| T <sub>op</sub>  | Operating junction temperature range                                                                 | - 40 to + 125 | °C |  |  |
| T <sub>stg</sub> | Storage temperature range                                                                            | - 55 to + 150 | °C |  |  |

Table 2. Electrical characteristics ( $T_{amb} = 25 \text{ °C}$ )

| Symbol            | Conditions                                      | Min. | Тур. | Max. | Unit |
|-------------------|-------------------------------------------------|------|------|------|------|
| $V_{BR}$          | Internal protection avalanche                   | 6    |      |      | V    |
| S <sub>dd11</sub> | From 10 MHz to 60 MHz, $T_j$ = -40 °C to 125 °C |      |      | -20  | dB   |

Figure 2. BroadR Reach application schematic



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EMIF02-01OABRY Characteristics

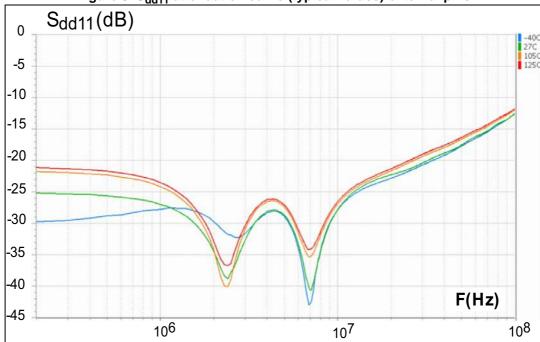
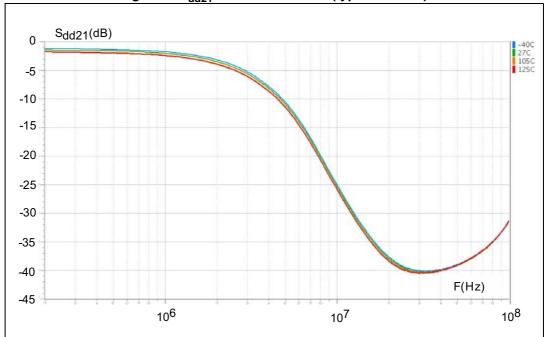


Figure 3. S<sub>dd11</sub> attenuation curve (typical values)-external pins





## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK<sup>®</sup> is an ST trademark.

#### 2.1 QFN package information

Figure 5. QFN package outline NX D2 b E2 see detail «F» 0.350 θ Detail «F» D Ε

**5**/

Table 3. QFN package mechanical data

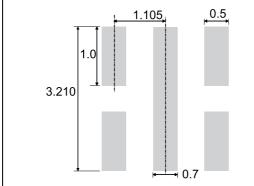
|      | Dimensions |             |      |       |                       |       |
|------|------------|-------------|------|-------|-----------------------|-------|
| Ref. |            | Millimeters |      |       | Inches <sup>(1)</sup> |       |
|      | Тур.       | Min.        | Max. | Тур.  | Min.                  | Max.  |
| Α    | 0.80       |             | 0.90 | 0.031 |                       | 0.035 |
| A1   | 0.00       |             | 0.05 | 0.000 |                       | 0.002 |
| A3   |            | 0.203       |      |       | 0.008                 |       |
| θ    | 0°         |             | 12°  | 0°    |                       | 12°   |
| b    | 0.45       |             | 0.55 | 0.018 |                       | 0.022 |
| D    | 2.95       |             | 3.05 | 0.116 |                       | 0.120 |
| E    | 2.95       |             | 3.05 | 0.116 |                       | 0.120 |
| е    |            | 2.21        |      |       | 0.88                  |       |
| L    | 0.85       |             | 0.95 | 0.33  |                       | 0.37  |
| N    |            | 6           |      |       | 0.236                 |       |
| D2   | 0.60       |             | 0.80 | 0.024 |                       | 0.031 |
| E2   | 2.90       |             | 3.10 | 0.114 |                       | 0.122 |

<sup>1.</sup> Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 6. Footprint recommendations

Figure 7. Marking

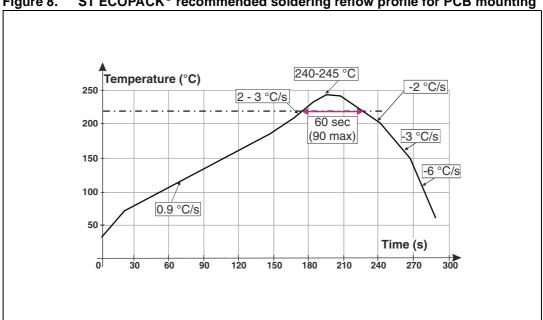
(in mm)



# 3 Recommendation on PCB assembly

## 3.1 Reflow profile

Figure 8. ST ECOPACK® recommended soldering reflow profile for PCB mounting

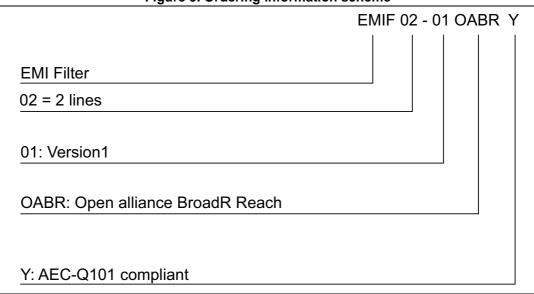


Note: Minimize air convection currents in the reflow oven to avoid component movement.

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# 4 Ordering information

Figure 9. Ordering information scheme



**Table 4. Ordering information** 

| Order code     | Marking             | Package | Weight   | Base qty | Delivery mode |
|----------------|---------------------|---------|----------|----------|---------------|
| EMIF02-01OABRY | MIF02-01OABRY 21BRY |         | 1.935 mg | 3000     | Tape and reel |

## 5 Revision history

**Table 5. Document revision history** 

| Date        | Revision | Changes         |
|-------------|----------|-----------------|
| 01-Sep-2015 | 1        | Initial release |

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